Heller Industries was founded in 1960 and pioneered convection reflow soldering in the 1970s. Over the years, Heller has partnered with its customers to continually refine the systems to satisfy advanced applications requirements. By embracing challenge and change, Heller has earned the position of World Leader in Reflow Technology.

Benefits of Partnering with the World Leader

In addition to getting the best oven technology, working with the industry leader carries many other important benefits:

- **Partnership**: By working closely with our customers, we provide the kind of V/O service and support that has come to be expected for Heller industries.

- **Corporate Strength and Longevity**: Over 40 years in the electronics industry gives us a solid corporate and management base that ensures stability and continued support.

- **Direct Access to Upper Management**: Our upper management staff are committed to understanding our customers' needs and input. We find that by listening we can better serve our customer.

- **Distributed “Lean” Manufacturing**: With facilities in China, Korea and Malaysia, we can provide “local” sourcing and localized “Lean” manufacturing expertise with a business model that provides a “local” presence that goes beyond simple manufacturing. Localized processing, troubleshooting, training and strategic support centers, Heller provides a “local” presence that goes far beyond simple manufacturing. Localized processing, troubleshooting, training and strategic support centers, Heller

By working closely with our customers, we provide the kind of V/O service and support that has come to be expected for Heller Industries. We welcome you to visit any of our three Centers for Excellence to learn about lead-free processing, troubleshooting, training and advanced applications solutions.

Combining our unmatched engineering expertise with a business model that focuses on regional manufacturing and training support centers, Heller provides a “local” presence that goes beyond simple manufacturing. Localized processing, troubleshooting, training and strategic support centers, Heller provides a “local” presence that goes beyond simple manufacturing.

---

**Advanced Technology for Demanding Processes**

**Mark III Models**

<table>
<thead>
<tr>
<th>Model</th>
<th>Oven Length</th>
<th># of Heated Zones</th>
<th># of Cooling Zones</th>
</tr>
</thead>
<tbody>
<tr>
<td>120”</td>
<td>340 cm</td>
<td>7 Top</td>
<td>1</td>
</tr>
<tr>
<td>175”</td>
<td>405 cm</td>
<td>9 Top</td>
<td>2</td>
</tr>
<tr>
<td>175”</td>
<td>405 cm</td>
<td>11 Bottom</td>
<td>2</td>
</tr>
<tr>
<td>232”</td>
<td>508 cm</td>
<td>13 Top</td>
<td>4</td>
</tr>
</tbody>
</table>

---

**Mark III Series Reflow System**

Advanced Technology for Demanding Processes
Recognized Leadership

Our focus on technology-driven solutions in partnership with our customers has been consistently recognized throughout the years by several industry agencies including two Vision Awards for new product innovation, two Market Leadership Award, two Service Excellence Awards, several awards for vendor excellence and appointments to prominent positions on Industry committees and Boards.

Certainly these awards and appointments validate our position; but more importantly, they confirm that Heller is at the forefront of the technology curve — constantly bringing new innovations to market faster and with greater impact than our competitors.

Process Control

Powered by ECD, this innovative software package provides three levels of process control: Oven CpK, Process CpK and Product FMECAA. The software ensures that all parameters are optimized and SPC reporting is fast and easy.

New Frame

More than simply beautiful, this new frame utilizes twice the insulation. This reduces heat loss and saves up to 40% on electricity costs!

Ultra-Parallel Conveyor System

First (4) lead screws ensures the tightest tolerances and parallelism — even on boards with 3mm clearance of the edges.

Enhanced Heater Modules

Provides three levels of process control: Oven CpK, Process CpK and Product FMEA. The software ensures that all parameters are optimized and SPC reporting is fast and easy.

Fastest Cooling Rates

The new blow thru cooling module provides cool rates of >3 deg C/Sec — even on LGA 775! That rate meets even the most demanding Lead-Free profile requirements!

New Flux System Virtually Eliminates Maintenance

This new flux collection system traps the flux in a separate collection box with easy to remove plates. As a result, the oven is kept clean — thus saving time consuming FMECAA. A collection jar captures the flux and can be removed while the oven is running for the ultimate in time savings!